

5 An improved method of attaching a semiconductor die to an organic substrate and an improved semiconductor package are herein disclosed. The die package comprises a die secured to a printed circuit board (PCB) with an adhesive tape. The adhesive tape may be of (single) or multi-layer construction. In one embodiment, a tri-layer tape is disclosed having a carrier layer sandwiched between two identical adhesive layers. In one embodiment, a method is disclosed utilizing a pressure sensitive, thermoset adhesive tape. In another embodiment, a method is  
10 disclosed utilizing a B-stageable thermoset adhesive. In yet another embodiment, a method using a pressure sensitive adhesive is disclosed. In still yet another embodiment, a method is disclosed wherein the adhesive is a hybrid material having both thermoset and thermoplastic components.

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